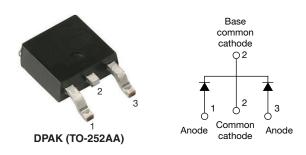
Vishay Semiconductors



Hyperfast Rectifier, 2 x 5 A FRED Pt[®]



PRIMARY CHARACTERISTICS								
I _{F(AV)}	2 x 5 A							
V _R	200 V							
V _F at I _F	0.74 V							
t _{rr} (typ.)	23 ns							
T _J max.	175 °C							
Package	DPAK (TO-252AA)							
Circuit configuration	Common cathode							

FEATURES

- · Hyperfast recovery time
- 175 °C max. operating junction temperature
- · Output rectification freewheeling
- Low forward voltage drop reduced Q_{rr} and soft recovery COMPLIANT HALOGEN
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS inverters or as freewheeling diodes. Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS											
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS							
Peak repetitive reverse voltage	V _{RRM}		200	V							
Average rectified forward current	I _{F(AV)}	T _C = 160 °C	10	^							
Non-repetitive peak surge current	I _{FSM}	T _J = 25 °C	80	A							
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C							

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 μA	200	-	-					
Forward voltage		I _F = 5 A	-	0.90	0.98	.,				
	V _F	I _F = 10 A - 0.9			1.15	V				
		I _F = 5 A, T _J = 150 °C	-	0.74	0.74 0.84					
		I _F = 10 A, T _J = 150 °C	-	0.84	1.05					
		$V_{\rm R} = V_{\rm R}$ rated	-	-	4					
Reverse leakage current per leg	I _R	$T_J = 125 \text{ °C}, V_R = V_R \text{ rated}$	-	-	40	μA				
		$T_J = 150 \text{ °C}, V_R = V_R \text{ rated}$	-	-	80					
Junction capacitance per leg	C _T	V _R = 600 V	-	17	-	pF				
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8	-	nH				

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FREE

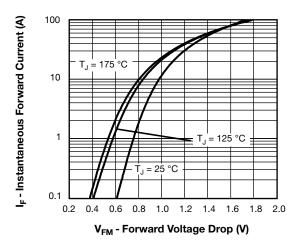


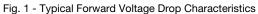
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DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25 \text{ °C}$ unless otherwise specified)											
PARAMETER	SYMBOL	TEST C	ONDITIONS	MIN.	TYP.	MAX.	UNITS				
		I _F = 1 A, dI _F /dt =	= 100 A/µs, V _R = 30 V	-	23	27					
Reverse recovery time	t _{rr}	T _J = 25 °C		-	21	-	ns				
		T _J = 125 °C		-	26	-					
Peak recovery current	I _{RRM}	T _J = 25 °C	$I_F = 5 A$	-	2	-	А				
		T _J = 125 °C	dl _F /dt = 200 A/µs V _B = 160 V	-	3.1	-	~				
Reverse recovery charge	Q _{rr}	T _J = 25 °C		-	20	-	nC				
neverse recovery charge	Qrr	T _J = 125 °C		-	41	-	nu				

THERMAL - MECHANICAL SPECIFICATIONS											
PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Maximum junction and storage tempe	T _J , T _{Stg}		-65	-	175	°C					
Thermal resistance, junction to case	per leg	R _{thJC}		-	2.7	3.2	°C/W				
	per device			-	1.35	1.6					
Approximate weight					0.3		g				
			0.01			oz.					
Marking device			Case style DPAK (TO-252AA)		10CW	H02FN					





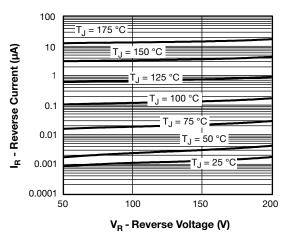


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

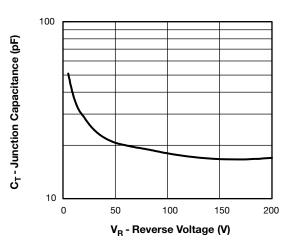


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

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VS-10CWH02FN-M3 www.vishay.com **Vishay Semiconductors** 10 Z_{thJC} - Thermal Impedance (°C/W) D = 0.5D = 02 1 D = 0.1D D = 0.02Single Pulse D = 0.01(Thermal Resistance) 0.1 1E-04 1E-03 1E-02 1E-05 1E-01 1E+00 t₁ - Rectangular Pulse Duration (s)

Fig. 4 - Maximum Thermal Impedance ZthJC Characteristics

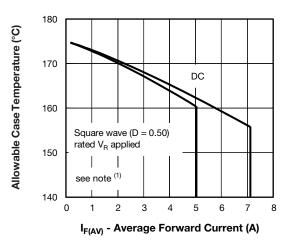
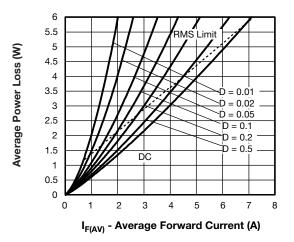
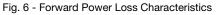


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current





Note

⁽¹⁾ Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$;

Pd = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6); Pd_{REV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R

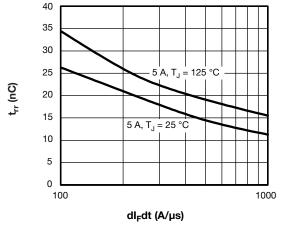


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

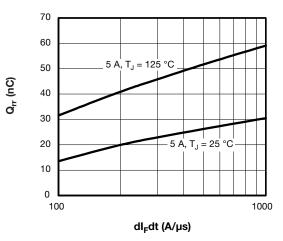


Fig. 8 - Typical Stored Charge vs. dl_F/dt

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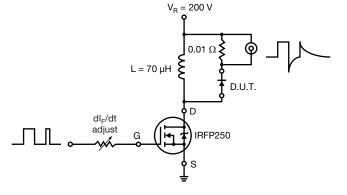


Fig. 9 - Reverse Recovery Parameter Test Circuit

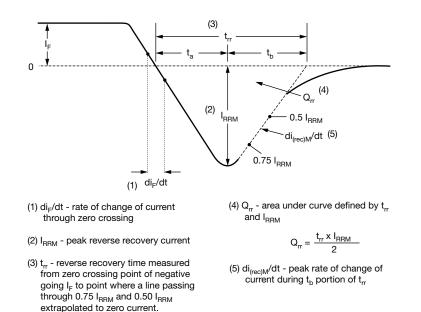


Fig. 10 - Reverse Recovery Waveform and Definitions

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Device code	VS-	10	с	w	ы	02	EN	TRL	-M3
Device code	v3-	10	C	vv	Н	02	FN	IKL	-141-2
		2	3	4	5	6	7	8	9
	1	- Visl	nay Sen	niconduc	ctors pro	oduct			
	2	- Cur	rent rati	ng (10 =	= 10 A)				
	3	- Circ	cuit conf	iguratior	า:				
		C =	commo	on catho	de				
	4	- Pac	kage id	entifier:					
		VV =	D-PAK						
	Ľ	- H=	hyperfa	ast recov	/ery				
	6 7	- Volt	tage rati	ng (02 =	= 200 V)				
	7	- FN	= TO-25	52AA					
	8	• N	one = tu	ibe					
		• TI	R = tape	e and ree	el				
		• TI	RL = tap	be and re	eel (left	orienteo	d)		
		• TI	RR = ta _l	pe and r	eel (righ	t orient	ed)		
	9	- Env	rironmer	ntal digit	:				
		-M3	s = halog	gen-free	, RoHS-	complia	ant and	termina	tions le

ORDERING INFORMATION (Example)										
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION								
VS-10CWH02FN-M3	75	Antistatic plastic tube								
VS-10CWH02FNTR-M3	2000	13" diameter reel								
VS-10CWH02FNTRL-M3	3000	13" diameter reel								
VS-10CWH02FNTRR-M3	3000	13" diameter reel								

LINKS TO RELATED DOCUMENTS								
Dimensions	www.vishay.com/doc?95627							
Part marking information	www.vishay.com/doc?95176							
Packaging information	www.vishay.com/doc?95033							
SPICE model	www.vishay.com/doc?95376							





D-PAK (TO-252AA) "M"

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	NOTES		MILLIN	IETERS	INC	HES	NOTES
STNIDUL	MIN.	MAX.	MIN.	MAX.	NOTES		SYMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
А	2.18	2.39	0.086	0.094			е	2.29	BSC	0.090	BSC	
A1	-	0.13	-	0.005			Н	9.40	10.41	0.370	0.410	
b	0.64	0.89	0.025	0.035			L	1.40	1.78	0.055	0.070	
b2	0.76	1.14	0.030	0.045			L1	2.74	BSC	0.108	REF.	
b3	4.95	5.46	0.195	0.215	3		L2	0.51 BSC		0.020 BSC		
С	0.46	0.61	0.018	0.024			L3	0.89	1.27	0.035	0.050	3
c2	0.46	0.89	0.018	0.035			L4	-	1.02	-	0.040	
D	5.97	6.22	0.235	0.245	5		L5	1.14	1.52	0.045	0.060	2
D1	5.21	-	0.205	-	3		Ø	0°	10°	0°	10°	
E	6.35	6.73	0.250	0.265	5		Ø1	0°	15°	0°	15°	
E1	4.32	-	0.170	-	3		Ø2	25°	35°	25°	35°	

Notes

⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994

⁽²⁾ Lead dimension uncontrolled in L5

⁽³⁾ Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad

(4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip

(5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

⁽⁶⁾ Dimension b1 and c1 applied to base metal only

⁽⁷⁾ Datum A and B to be determined at datum plane H

⁽⁸⁾ Outline conforms to JEDEC[®] outline TO-252AA



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